Preferred Device

# **Switching Diode**

• High-Speed Switching Applications

• Lead Finish: 100% Matte Sn (Tin)

• Qualified Reflow Temperature: 260°C

• Extremely Small SOD-523 Package

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Continuous Reverse Voltage	$V_R$	75	Vdc
Peak Forward Current	I <sub>F</sub>	200	mAdc
Peak Forward Surge Current	I <sub>FM(surge)</sub>	500	mAdc

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) T <sub>A</sub> = 25°C	P <sub>D</sub>	200	mW
Derate above 25°C		1.57	mW/°C
Thermal Resistance Junction-to-Ambient	$R_{\theta JA}$	635	°C/W
Junction and Storage Temperature	T <sub>J</sub> , T <sub>stg</sub>	–55 to 150	°C

- 1. FR-4 Minimum Pad.
- 2. 300 mW for 1 in. copper.

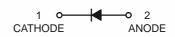
## ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C unless otherwise noted)

	`			,
Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS	M'DID.			
Reverse Voltage Leakage Current $(V_R = 75 \text{ Vdc})$ $(V_R = 75 \text{ Vdc}, T_J = 150^{\circ}\text{C})$ $(V_R = 25 \text{ Vdc}, T_J = 150^{\circ}\text{C})$	I <sub>R</sub>	- - -	1.0 50 30	μAdc
Reverse Breakdown Voltage (I <sub>BR</sub> = 100 μAdc)	V <sub>(BR)</sub>	75	-	Vdc
Forward Voltage (I <sub>F</sub> = 1.0 mAdc) (I <sub>F</sub> = 10 mAdc) (I <sub>F</sub> = 50 mAdc) (I <sub>F</sub> = 150 mAdc)	V <sub>F</sub>	2-m	715 855 1000 1250	mV
Diode Capacitance (V <sub>R</sub> = 0, f = 1.0 MHz)	C <sub>D</sub>	-	2.0	pF
Forward Recovery Voltage (I <sub>F</sub> = 10 mAdc, t <sub>r</sub> = 20 ns)	V <sub>FR</sub>	-	1.75	Vdc
Reverse Recovery Time (I <sub>F</sub> = I <sub>R</sub> = 10 mAdc, R <sub>L</sub> = 50 $\Omega$ )	t <sub>rr</sub>		6.0	ns
Stored Charge (Is = 10 mAdc to $V_R = 5.0 \text{ Vdc}$ , $R_1 = 500 \Omega$ )	Q <sub>S</sub>	-	45	pC



# ON Semiconductor®

http://onsemi.com





MARKING DIAGRAM

SOD-523 CASE 502 PLASTIC



A6 = Specific Device Code

M = Month Code

= Pb–Free Package

(Note: Microdot may be in either location)

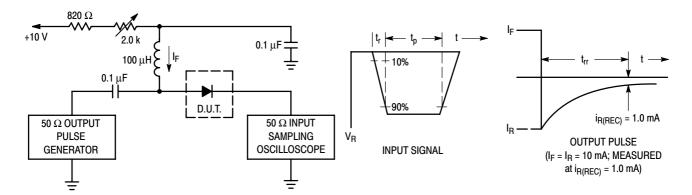
### ORDERING INFORMATION

1	Device	Package	Shipping†		
ĺ	BAS16XV2T1	SOD-523	3000/Tape & Reel		
	BAS16XV2T1G	SOD-523 (Pb-Free)	3000/Tape & Reel		

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

dzsc.com



Notes: 1. A 2.0  $k\Omega$  variable resistor adjusted for a Forward Current (IF) of 10 mA.

- 2. Input pulse is adjusted so  $I_{\mbox{\scriptsize R(peak)}}$  is equal to 10 mA.
- 3. tn » trr

Figure 1. Recovery Time Equivalent Test Circuit

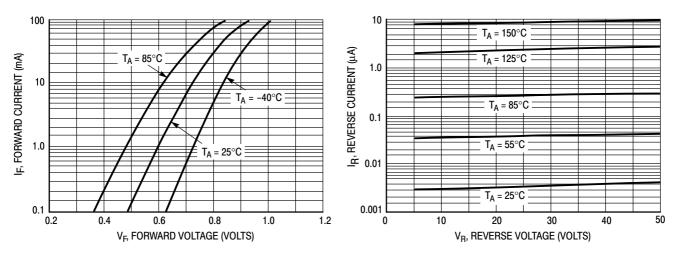


Figure 2. Forward Voltage

Figure 3. Leakage Current

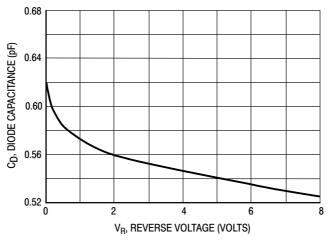
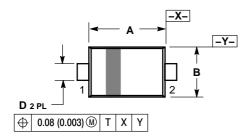
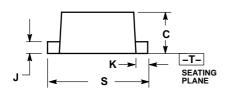


Figure 4. Capacitance

#### **PACKAGE DIMENSIONS**

SOD-523 CASE 502-01 **ISSUE B** 





- NOTES:

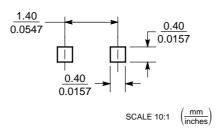
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2. CONTROLLING DIMENSION: MILLIMETER.

  3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	1.10	1.20	1.30	0.043	0.047	0.051	
В	0.70	0.80	0.90	0.028	0.032	0.035	
С	0.50	0.60	0.70	0.020	0.024	0.028	
D	0.25	0.30	0.35	0.010	0.012	0.014	
J	0.07	0.14	0.20	0.0028	0.0055	0.0079	
K	0.15	0.20	0.25	0.006	0.008	0.010	
S	1.50	1.60	1.70	0.059	0.063	0.067	

## **SOLDERING FOOTPRINT\***



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

#### **PUBLICATION ORDERING INFORMATION**

#### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 61312, Phoenix, Arizona 85082–1312 USA Phone: 480–829–7710 or 800–344–3860 Toll Free USA/Canada Fax: 480–829–7709 or 800–344–3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800–282–9855 Toll Free USA/Canada

Japan: ON Semiconductor, Japan Customer Focus Center 2–9–1 Kamimeguro, Meguro–ku, Tokyo, Japan 153–0051 Phone: 81–3–5773–3850

ON Semiconductor Website: http://onsemi.com

Order Literature: http://www.onsemi.com/litorder

For additional information, please contact your local Sales Representative.